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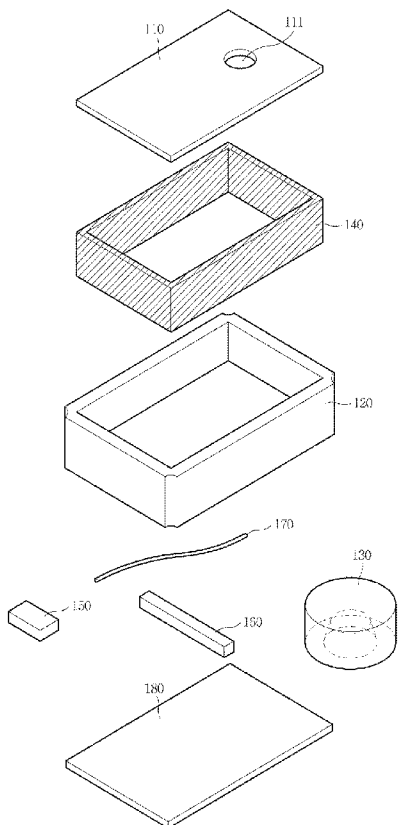
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(54) Title: CONDENSER MICROPHONE USING THE CERAMIC PACKAGE WHOSE INSIDE IS ENCOMPASSED BY METAL OR CONDUCTIVE MATERIALS

[Fig. 2]



(57) Abstract: Provided is a condenser microphone. The condenser microphone includes: a substrate disposed on a micro electro mechanical system (MEMS) microphone chip and a circuit part; a package having a ring shape and disposed on the substrate, the package surrounding the MEMS microphone chip and the circuit part; an insertion part having a ring shape and formed of a conductive material, the insertion part being attached to an inner wall of the package; and an upper plate completely covering the package, the upper plate having an acoustic hole through which sound passes. In addition, the condenser microphone includes: a substrate disposed on a MEMS microphone chip and a circuit part; a package disposed on the substrate and covering the MEMS microphone chip and the circuit part, the package having an acoustic hole through which sound passes; and an insertion part attached to an inner wall of the package, the insertion part being formed of a conductive material.



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